



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Cohen et al.

Serial No.: 09/206,027

Filed: December 4, 1998

For: Plasma Preclean With Argon,  
Helium, and Hydrogen Gases

Group Art Unit: 1765

Examiner: Lan Vinh

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

|   |                                       |
|---|---------------------------------------|
| CERTIFICATE OF MAILING<br>37 C.F.R. 1.8   |                                       |
| I hereby certify that this correspondence is being deposited on<br><u>5/17</u> , 2000, with the U. S. Postal Service as First<br>Class Mail in an envelope addressed to: Assistant Commissioner for<br>Patents, Washington, D.C. 20231. |                                       |
| <u>5/17/00</u><br>Date  | <u>B. Todd Patterson</u><br>Signature |

## RESPONSE TO OFFICE ACTION DATED FEBRUARY 17, 2000

In response to the Office Action dated February 17, 2000, having a shortened statutory period for response set to expire on May 17, 2000, please enter the following amendment and reconsider the claims pending in the application for reasons discussed below. Please charge the amount of \$54.00 and any additional fees necessary for three (3) excess dependent claims to Deposit Account No. 20-0782/AMAT/3049/ISM/ISMB/DV of Thomason, Moser & Patterson, L.L.P.

IN THE CLAIMS:

Please amend the claims as follows:

1. A method for processing a substrate, comprising exposing a patterned substrate surface to a plasma comprising argon, helium and hydrogen in a processing chamber.
2. The method of claim 1, wherein the plasma comprises less than about 75% by volume of